The Chroma 3160 Handler is a productive pick & place system for high volume multi-site IC testing. Saving floor space, time and cost, the 3160 can increase production productivity and efficiency with its innovative design. The system is configurable for Single, Dual or Quad test sites and can be upgraded to provide an Active Thermal Control (ATC) System to test the DUT up to 150°C.

The Chroma 3160 is also capable of handling various package sizes and types then bins them according to customer specified test results. The system has a reliable handling mechanism, is compatible with standard Conversion Kits and has a streamlined automation sequence, which results in high throughput with low jam rate. Its precisely adjustable contact force, fine alignment positioning and various device sensors also reduces unexpected device damage and helps extend test socket lifetime while maintaining or increasing production yields.

**QUAD SITE FT HANDLER**

**MODEL 3160**

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**KEY FEATURES**

- In Line 1*4 or Matrix 2*2 Flexible DUT Configuration
- 10K pieces Throughput (Dummy Run)
- Programmable Pitch Probes
- Side Mount Capable
- Air Damper Buffer to Reduce Contact Force Impact
- Anti Double Stack & Positioning Protection
- Contact Force Learning
- Color Tray Mode Available
- Yield Monitor (individual contact head)
- Universal Change Kits
- RCAA (Real-time Camera Assist Alignment) for Engineering Adjustment (Patent Pending)
## SPECIFICATIONS

<table>
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<th>Model</th>
<th>3160</th>
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| **Dimensions & Weight** | Dimensions: 1,700 mm (W) x 1,300 mm (D) x 2,000 mm (H)  
Weight: Approx. 900 kg |
| **Facility** | Power Source: AC220, 50 / 60Hz Single Phase, 10KVA Max.  
Compressed Air: 0.5MPa or more (dry & clean air), Consumption 120l/min, constant supply |
| **Applicable Device** | Package Carried on Type: BGA, QFP, CSP, PLCC, TSOP, PGA… etc.  
Package Size: 3 mm x 3 mm to 50 mm x 50 mm |
| **Contact Mode** | Direct Contact / Drop and Press |
| **Interface** | TTL  
RS232 / GPIB (option) |
| **Multiple Site** | 4 sites (In line 1 x 4 pitch X =40mm; 2 x 2 Matrix type option ) |
| **Contact Area** | Test Site: Single, Dual, Quad sites (In-Line)  
Test Head Area: 550 mm (from socket center), Height: 1,000 mm (900/1, 100mm option) |
| **Index Time** | 0.38 sec (tester communication time excluded) |
| **Jam Rate** | 1/10000 |
| **Applicable Tray** | JEDEC 135.9mm (W) x 315 mm (L)  
Applicable tray thickness: 7.62mm, 12.2mm |
| **Category** | 6 categories (3 auto, 3 manual) |
| **Binning** | 16 bin signal for TTL |
| **Contact Force** | 50 kgf (accuracy ± 1 kgf)  
80 kgf (option) |
| **Temperature** | Operating Mode: Ambient |
| **High Temperature (Option)** | Operating Mode: 40°C ~ 150°C (heating time: within 30 min.)  
Accuracy: Contact Head ± 3 °C, Pre-heater ± 5 °C |

All specifications are subject to change without notice.

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**Loading**  
**In-line Test Site**  
**Unloading**